

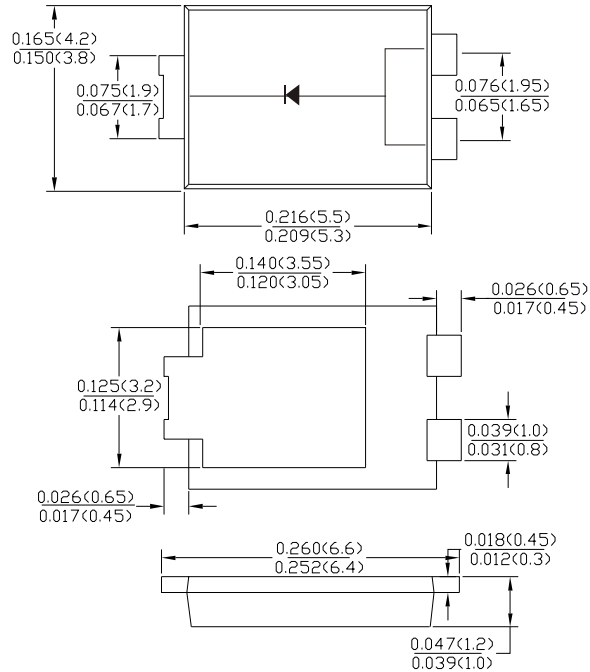
Features

- Schottky Barrier Chip
- High Thermal Reliability
- Patented Super Barrier Rectifier Technology
- High Forward Surge Capability
- Ultra Fow Power Loss,High Efficiency
- Excellent High Temperature Stability
- Plastic material-UL flammability 94V-0

Mechanical Data

- Case: TO-277, molded plastic
- Terminals:Plated Leads Solderable per MIL-STD-202,Method 208
- Polarity:Cathode Band
- Mounting Position:Any
- Marking:Type Number
- Lead Free:For RoHS/Lead Free Version

TO-277



Dimensions inches and (milimeters)

Maximum Ratings and Electrical Characteristics @T_A =25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbol	SL 1045	SL 1050	SL 1060	SL 1080	SL 10100	SL 10150	Unit	
Peak Repetitive Reverse Voltage	V _{RRM}								
Working Peak Reverse Voltage	V _{RWM}	45	50	60	80	100	150	V	
DC blocking voltage	V _{DC}								
RMS Rectified Voltage	V _{R(RMS)}	32	35	42	56	70	105	V	
Average Rectified Output Current (Note1)	I _O	10						A	
Non-Repetitive Peak Forward Surge 8.3ms Single Half Sine-Wave Superimposed on rated load (JEDEC Method) (Note2)	I _{FSM}	250						A	
Forward Voltage Drop T _A =25°C @ I _F =10A	V _{FM}	0.45	0.47	0.50	0.75		0.78	V	
Peak Reverse Current T _A =25°C At Rated DC Blocking Voltage T _A =100°C	I _R	0.3						15	mA
Typical Thermal Resistance Junction to Ambient	R _{θJA} R _{θJL}	80						15	°C/W
Operating junction temperature range	T _J	-55 to +150						°C	
storage temperature range	T _{STG}	-55 to +150						°C	

Note:1. Valid Provided that are kept at ambient temperature at a distance of 9.5mm from the case.

2. Fr-4pcb. 2oz. Copper, minimum recommend pad layout . 18.8mm×14.4. Anode pad dimensions 5.6mm×14.4mm.

Fig.1 - Forward Current Derating Curve

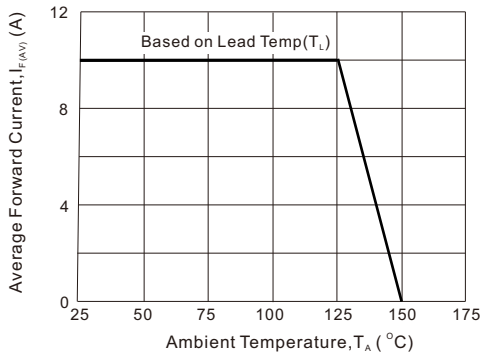


Fig2 : Instantaneous Forward Voltage

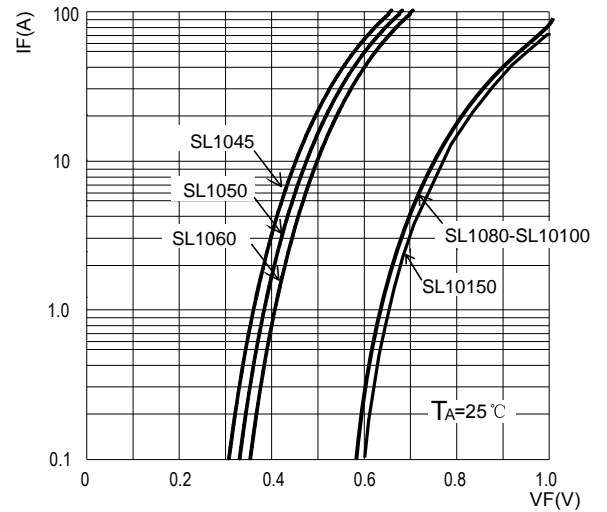


Fig3: Surge Forward Current Capability

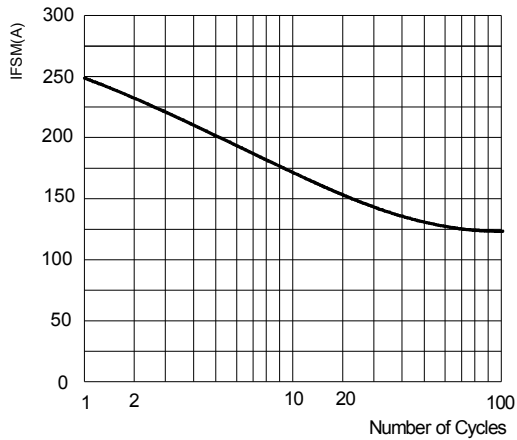


Fig4: Typical Reverse Characteristics

